

Features

- Split Gate Trench MOSFET Technology
- · Excellent Package for Heat Dissipation
- High Density Cell Design for Low R_{DS(ON)}
- · Halogen Free. "Green" Device (Note 1)
- Epoxy Meets UL 94 V-0 Flammability Rating
- Lead Free Finish/RoHS Compliant ("P" Suffix Designates RoHS Compliant. See Ordering Information)

Maximum Ratings

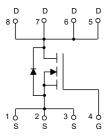
- Operating Junction Temperature Range : -55°C to +150°C
- Storage Temperature Range: -55°C to +150°C
- Thermal Resistance: 22.3°C/W Junction to Ambient(t≤10s)⁽²⁾
- Thermal Resistance: 40.7°C/W Junction to Ambient(Steady-State)⁽²⁾
- Thermal Resistance: 2.45°C/W Junction to Case(Steady-State)

Parameter	Symbol	Rating	Unit
Drain-Source Voltage	V _{DS}	80	V
Gate-Source Volltage	V _{GS}	±20	V
Continuous Drain Current	I _D	100	Α
Pulsed Drain Current ⁽³⁾	I _{DM}	400	Α
Total Power Dissipation ⁽⁴⁾	P _D	51	W
Single Pulsed Avalanche Energy ⁽⁵⁾	E _{AS}	600	mJ

Note:

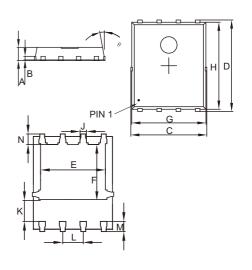
- 1. Halogen free "Green" products are defined as those which contain <900ppm bromine, <900ppm chlorine (<1500ppm total Br + Cl) and <1000ppm antimony compounds.
- 2. The value of $R_{\theta JA}$ is measured with the device mounted on $1in^2$ FR-4 board with 2oz. Copper, in a still air environment with T_A =25°C. The Power dissipation P_{DSM} is based on $R_{\theta JA}$ t≤ 10s and the maximum allowed junction temperature of 150°C. The value in any given application depends on the user's specific board design.
- 3. Repetitive rating; pulse width limited by max. junction temperature.
- 4. P_D is based on max. junction temperature, using junction-case thermal resistance.
- 5. T_J =25°C, V_{DD} =50V, V_{GS} =10V, L=3mH, I_{AS} =20A.

Internal Structure



N-CHANNEL MOSFET

DFN5060



	DIMENSIONS					
DIM	INCHES		MM		NOTE	
Dilvi	MIN	MAX	MIN	MAX	NOIL	
Α	0.031	0.047	0.80	1.20		
В	0.010		0.254		TYP.	
С	0.193	0.222	4.90	5.64		
D	0.232	0.250	5.90	6.35		
Е	0.148	0.167	3.75	4.25		
F	0.126	0.154	3.20	3.92		
G	0.189	0.213	4.80	5.40		
Н	0.222	0.239	5.65	6.06		
K	0.045	0.059	1.15	1.50		
J	0.012	0.020	0.30	0.50		
L	0.046	0.054	1.17	1.37		
M	0.012	0.028	0.30	0.71		
N	0.016	0.028	0.40	0.71		

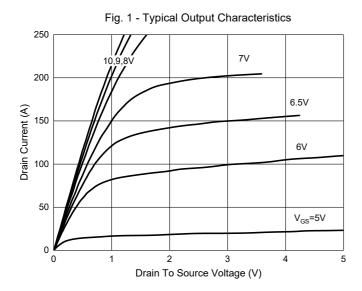


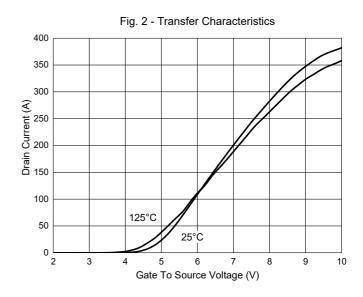
Electrical Characteristics @ 25°C (Unless Otherwise Specified)

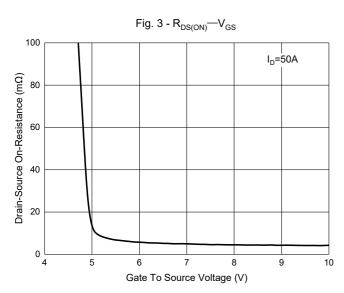
Parameter	Symbol	Test Conditions	Min	Тур	Max	Unit	
Static Characteristics			'				
Drain-Source Breakdown Voltage	V _{(BR)DSS}	V _{GS} =0V, I _D =250μA	80			V	
Gate-Source Leakage Current	I _{GSS}	V_{DS} =0V, V_{GS} =±20V			±100	nA	
Zero Gate Voltage Drain Current	I _{DSS}	V _{DS} =80V, V _{GS} =0V			1	μA	
Gate-Threshold Voltage	V _{GS(th)}	$V_{DS}=V_{GS}$, $I_{D}=250\mu A$	2	3	4	V	
Drain-Source On-Resistance	R _{DS(on)}	V _{GS} =10V, I _D =20A		3.6	4.5	mΩ	
Gate Resistance	R_g	F=1 MHz, Open drain		2		Ω	
Diode Characteristics	-		,				
Continuous Body Diode Current	Is				100	А	
Diode Forward Voltage	V _{SD}	V _{GS} =0V, I _S =20A		0.8	1.2	V	
Reverse Recovery Time	t _{rr}	L 504 H / H 4004 /		44		ns	
Reverse Recovery Charge	Q _{rr}	I _F =50A, dI _F /dt=100A/μs		50		nC	
Dynamic Characteristics	-		,		•		
Input Capacitance	C _{iss}			5469			
Output Capacitance	C _{oss}	V _{DS} =40V,V _{GS} =0V,f=1MHz		849		pF	
Reverse Transfer Capacitance	C _{rss}			37			
Total Gate Charge	Q_g			73			
Gate-Source Charge	Q _{gs}	V _{DS} =40V,V _{GS} =10V,I _D =50A		25		nC	
Gate-Drain Charge	Q_{gd}			12			
Turn-On Delay Time	t _{d(on)}			27			
Turn-On Rise Time	t _r	V _{DD} =40V, V _{GS} =10V,		32			
Turn-Off Delay Time	t _{d(off)}	$R_{GEN}=3\Omega$, $I_{DS}=50A$		54		ns	
Turn-Off Fall Time	t _f			17			

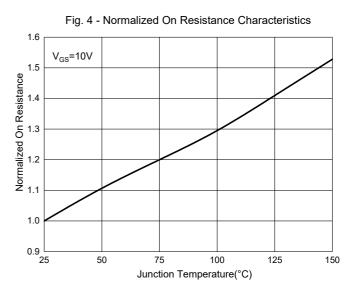


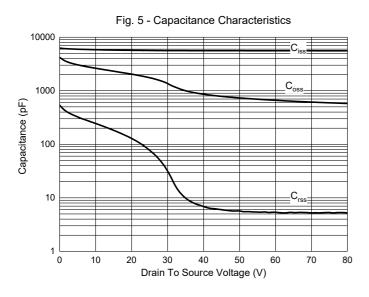
Curve Characteristics

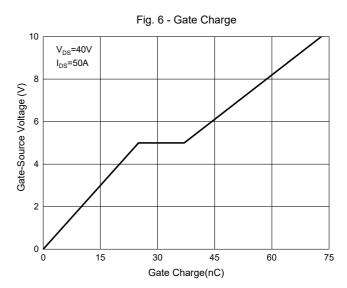














Curve Characteristics

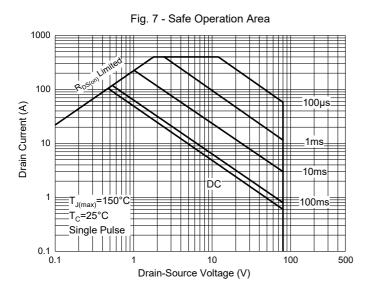
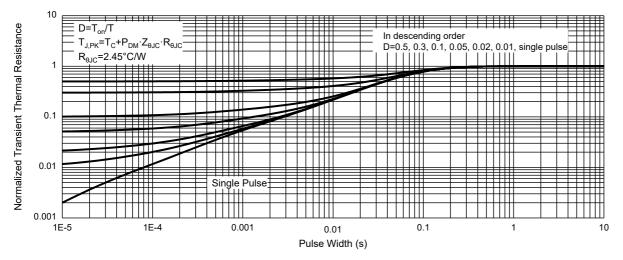


Fig. 8 - Normalized Transient Thermal Impedance



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Ordering Information

Device	Packing
Part Number-TP	Tape&Reel: 5Kpcs/Reel

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